

### FEATURES

- Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.
- Available as non-RoHS (Sn/Pb plating), standard, and as RoHS by adding "-PBF" suffix.

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
<b>Peak repetitive off-state voltage<sup>(1)</sup></b> ( $T_j = -40$ to $+110^\circ\text{C}$ , sine wave, 50 to 60Hz, gate open)			
MCR100-3		100	
MCR100-4	$V_{\text{DRM}}$	200	V
MCR100-5	$V_{\text{RRM}}$	300	
MCR100-6		400	
MCR100-7		500	
MCR100-8		600	
<b>On-state RMS current</b> (180° conduction angles, $T_c = 80^\circ\text{C}$ )	$I_{\text{T(RMS)}}$	0.8	A
<b>Peak non-repetitive surge current</b> (half-cycle, sine wave, 60Hz, $T_j = 25^\circ\text{C}$ )	$I_{\text{TSM}}$	10	A
<b>Circuit fusing consideration</b> ( $t = 8.3\text{ms}$ )	$I^2t$	0.415	$\text{A}^2\text{s}$
<b>Forward peak gate power</b> (pulse width $\leq 1.0\mu\text{s}$ , $T_A = 25^\circ\text{C}$ )	$P_{\text{GM}}$	0.1	W
<b>Forward average gate power</b> ( $t = 8.3\text{ms}$ , $T_A = 25^\circ\text{C}$ )	$P_{\text{G(AV)}}$	0.10	W
<b>Forward peak gate current</b> (pulse width $\leq 1.0\mu\text{s}$ , $T_A = 25^\circ\text{C}$ )	$I_{\text{GM}}$	1.0	A
<b>Reverse peak gate voltage</b> (pulse width $\leq 1.0\mu\text{s}$ , $T_A = 25^\circ\text{C}$ )	$V_{\text{GRM}}$	5.0	V
<b>Operating junction temperature range @ rated <math>V_{\text{RRM}}</math> and <math>V_{\text{DRM}}</math></b>	$T_j$	-40 to +110	$^\circ\text{C}$
<b>Storage temperature range</b>	$T_{\text{stg}}$	-40 to +150	$^\circ\text{C}$

Note 1:  $V_{\text{DRM}}$  and  $V_{\text{RRM}}$  for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Maximum	Unit
<b>Thermal resistance, junction to case</b>	$R_{\theta\text{JC}}$	75	$^\circ\text{C}/\text{W}$
<b>Thermal resistance, junction to ambient</b>	$R_{\theta\text{JA}}$	200	$^\circ\text{C}/\text{W}$
<b>Lead solder temperature</b> (lead length $< 1/16''$ from case, 10s max)	$T_L$	260	$^\circ\text{C}$

### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
<b>Peak forward or reverse blocking current<sup>(2)</sup></b> ( $V_{AK} = \text{Rated } V_{DRM} \text{ or } V_{RRM}, R_{GK} = 1k\Omega$ ) $T_C = 25^\circ\text{C}$ $T_C = 110^\circ\text{C}$	$I_{DRM}$ $I_{RRM}$	- -	- -	10 100	$\mu\text{A}$
<b>ON CHARACTERISTICS</b>					
<b>Peak forward on-state voltage<sup>*</sup></b> ( $I_{TM} = 1.0\text{A peak, @ } T_A = 25^\circ\text{C}$ )	$V_{TM}$	-	-	1.7	V
<b>Gate trigger current (continuous dc)<sup>(3)</sup></b> ( $V_{AK} = 7\text{V}, R_L = 100\Omega, T_C = 25^\circ\text{C}$ )	$I_{GT}$	-	40	200	$\mu\text{A}$
<b>Holding current<sup>(2)</sup></b> ( $V_{AK} = 7\text{V}$ , initiating current = 20mA) $T_C = 25^\circ\text{C}$ $T_C = -40^\circ\text{C}$	$I_H$	- -	0.5 -	5.0 10	mA
<b>Latch current</b> ( $V_{AK} = 7\text{V}, I_g = 200\mu\text{A}$ ) $T_C = 25^\circ\text{C}$ $T_C = -40^\circ\text{C}$	$I_L$	- -	0.6 -	10 15	mA
<b>Gate trigger voltage (continuous dc)<sup>(3)</sup></b> ( $V_{AK} = 7\text{V}, R_L = 100\Omega$ ) $T_C = 25^\circ\text{C}$ $T_C = -40^\circ\text{C}$	$V_{GT}$	- -	0.62 -	0.8 1.2	V
<b>DYNAMIC CHARACTERISTICS</b>					
<b>Critical rate of rise of off-state voltage</b> ( $V_D = \text{rated } V_{DRM}$ , exponential waveform, $R_{GK} = 1000\Omega, T_J = 110^\circ\text{C}$ )	$dv/dt$	20	35	-	V/ $\mu\text{s}$
<b>Critical rate of rise of on-state current</b> ( $I_{PK} = 20\text{A}, PW = 10\mu\text{sec}, di_G/dt = I_{gt} = 20\text{mA}$ )	$di/dt$	-	-	50	A/ $\mu\text{s}$

Note 2:  $R_{GK} = 1000\Omega$  included in measurement.

Note 3: Does not include  $R_{GK}$  in measurement.

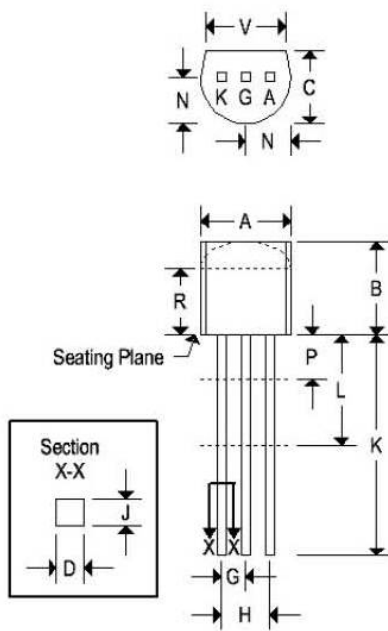
\* Pulse test: pulse width  $\leq 1.0\text{ms}$ , duty cycle  $\leq 1\%$ .

# MCR100 SERIES

## SILICON CONTROLLED RECTIFIERS

### MECHANICAL CHARACTERISTICS

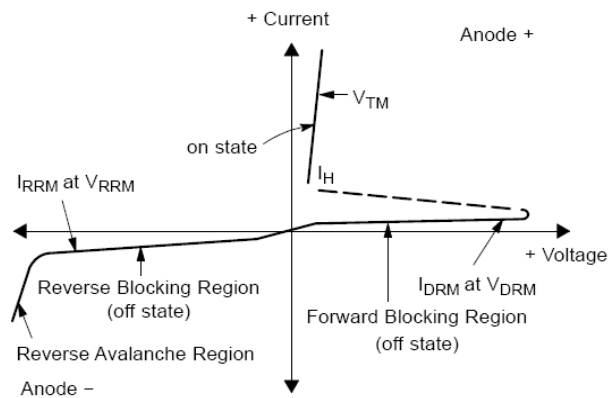
Case:	TO-92
Marking:	Body painted, alpha-numeric
Pin out:	See below



	TO-92			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.175	0.205	4.450	5.200
B	0.170	0.210	4.320	5.330
C	0.125	0.165	3.180	4.190
D	0.016	0.022	0.410	0.550
F	0.016	0.019	0.410	0.480
G	0.045	0.055	1.150	1.390
H	0.095	0.105	2.420	2.660
J	0.015	0.020	0.390	0.500
K	0.500	-	12.700	-
L	0.250	-	6.350	-
N	0.080	0.105	2.040	2.660
P	-	0.100	-	2.540
R	0.115	-	2.930	-
V	0.135	-	3.430	-

### Voltage Current Characteristic of SCR

Symbol	Parameter
$V_{DRM}$	Peak Repetitive Off State Forward Voltage
$I_{DRM}$	Peak Forward Blocking Current
$V_{RRM}$	Peak Repetitive Off State Reverse Voltage
$I_{RRM}$	Peak Reverse Blocking Current
$V_{TM}$	Peak On State Voltage
$I_H$	Holding Current



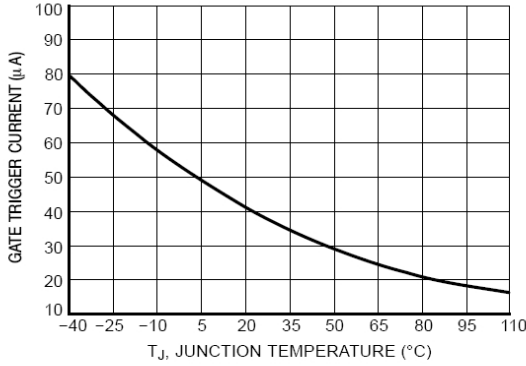


Figure 1. Typical Gate Trigger Current versus Junction Temperature

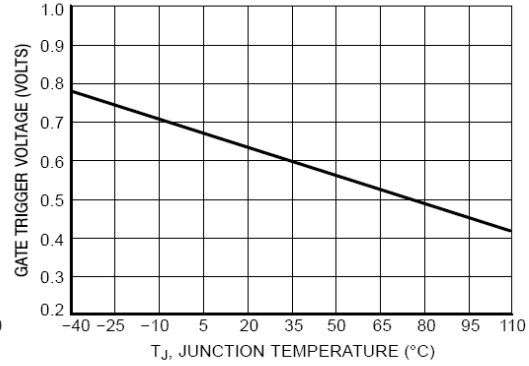


Figure 2. Typical Gate Trigger Voltage versus Junction Temperature

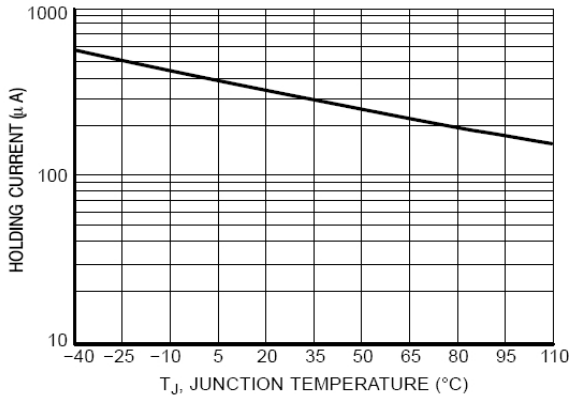


Figure 3. Typical Holding Current versus Junction Temperature

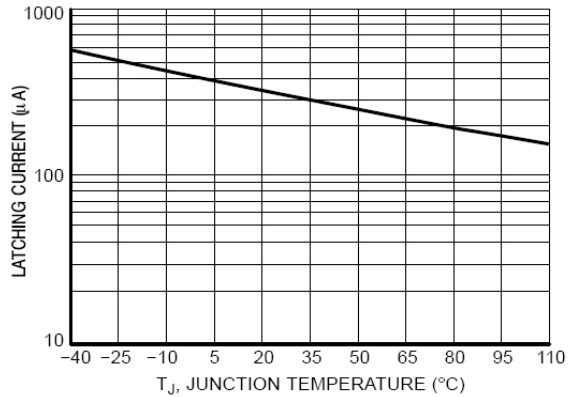


Figure 4. Typical Latching Current versus Junction Temperature

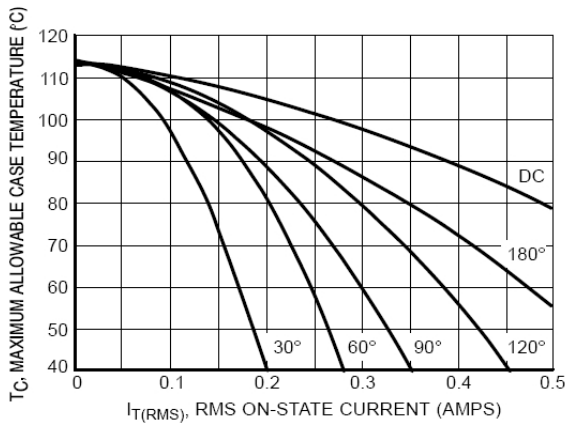


Figure 5. Typical RMS Current Derating

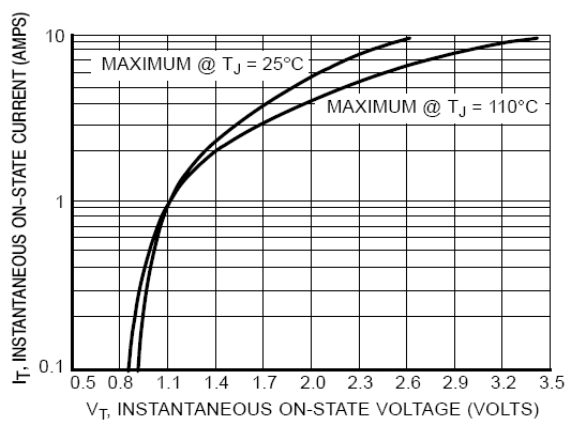


Figure 6. Typical On-State Characteristics